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Electronic Patent Application Submission

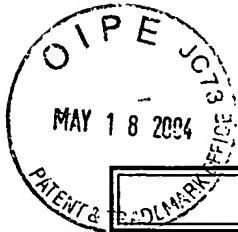
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Application ID: 10774893
Title of Invention: LEADFRAME FOR
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First Named Inventor: HYUNG LEE
Domestic/Foreign Application: Domestic Application
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TRANSMITTAL

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Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE	
Application Number:	10/774893	
Date:	2004-02-09	
First Named Applicant:	HYUNG JU LEE	
Confirmation Number:	8761	
Attorney Docket Number:	AMKOR006C	
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Submitted by:	Elec. Sign.	Sign. Capacity
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted	Files	
us-ids	ids1-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE						
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Confirmation Number:	8761						
First Named Applicant:	HYUNG LEE						
Attorney Docket Number:	AMKOR006C						
Art Unit:	2811						
Search string:	(2596993 or 3435815 or 3734660 or 3838984 or 4054238 or 4189342 or 4258381 or 4289922 or 4301464 or 4332537 or 4417266 or 4451224 or 4530152 or 4541003 or 4646710 or 4707724 or 4727633 or 4737839 or 4756080 or 4812896 or 4862245 or 4862246 or 4907067 or 4920074 or 4935803 or 4942454 or 4987475 or 5018003 or 5029386 or 5041902 or 5057900 or 5059379 or 5065223 or 5070039 or 5087961 or 5091341 or 5096852 or 5118298 or 5122860 or 5134773 or 5151039 or 5157475 or 5157480 or 5168368 or 5172213 or 5172214 or 5175060 or 5200362 or 5200809 or 5214845 or 20010008305 or 20010014538 or 20010011654 or 20020024122 or 20020027297 or 20020140061 or 20020140068 or 20020163015 or 20030030131 or 20030073265).pn.)						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	2596993	1952-05-20	S.L. Gookin			
	2	3435815	1969-04-01	Forcier			
	3	3734660	1973-05-22	Davies et al.			
	4	3838984	1974-10-01	Crane et al.			
	5	4054238	1977-10-18	Lloyd et al.			
	6	4189342	1980-02-19	Kock			
	7	4258381	1981-03-24	Inaba			

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8	4289922	1981-09-15	Devlin
9	4301464	1981-11-17	Otsuki et al.
10	4332537	1982-06-01	Slepcevic
11	4417266	1983-11-22	Grabbe
12	4451224	1984-05-29	Harding
13	4530152	1985-07-23	Roche et al.
14	4541003	1985-09-10	Otsuka et al.
15	4646710	1987-04-03	Schmid et al.
16	4707724	1987-11-17	Suzuki et al.
17	4727633	1988-03-01	Herrick
18	4737839	1988-04-12	Burt
19	4756080	1988-07-12	Thorp, Jr. et al.
20	4812896	1989-03-14	Rothgery et al.
21	4862245	1989-08-29	Pashby et al.
22	4862246	1989-08-29	Masuda et al.
23	4907067	1990-03-06	Derryberry
24	4920074	1990-04-24	Shimizu et al.
25	4935803	1990-06-19	Kalfus et al.
26	4942454	1990-07-17	Mori et al.
27	4987475	1991-01-22	Schlesinger et al.
28	5018003	1991-05-21	Yasunaga
29	5029386	1991-07-09	Chao et al.
30	5041902	1991-08-20	McShane
31	5057900	1991-10-15	Yamazaki
32	5059379	1991-10-22	Tsutsumi et al.
33	5065223	1991-11-12	Matsuki et al.
34	5070039	1991-12-03	Johnson et al.
35	5087961	1992-02-11	Long et al.
36	5091341	1992-02-25	Asada et al.
37	5096852	1992-03-17	Hobson
38	5118298	1992-06-02	Murphy
39	5122860	1992-06-16	Kichuchi et al.
40	5134773	1992-08-04	LeMaire et al.
41	5151039	1992-09-29	Murphy
42	5157475	1992-10-20	Yamaguchi
43	5157480	1992-10-20	McShane et al.

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44	5168368	1992-12-01	Gow, 3rd et al.
45	5172213	1992-12-15	Zimmerman
46	5172214	1992-12-15	Casto
47	5175060	1992-12-29	Enomoto et al.
48	5200362	1993-04-06	Lin et al.
49	5200809	1993-04-06	Kwon
50	5214845	1993-06-01	King et al.

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010008305	2001-07-19	MCLELLAN ET AL.			
	2	20010014538	2001-08-16	KWAN ET AL.			
	3	20010011654	2002-01-31	KIMURA			
	4	20020024122	2002-02-28	JUNG ET AL.			
	5	20020027297	2002-03-07	IKENAGA ET AL.			
	6	20020140061	2002-10-03	LEE			
	7	20020140068	2002-10-03	LEE ET AL.			
	8	20020163015	2002-11-07	LEE ET AL.			
	9	20030030131	2003-02-13	LEE ET AL.			
	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date